

NP/NPE-free (meet REACH requirement) — 不含壬基酚 (符合歐盟REACH環保規範)

NP (Nonyl Phenol) / NPE (Nonyl Phenol Ethoxylates) are generally used as surfactant. However, due to health and environmental hazards, NP/NPE has been banned in EU.

壬基酚一般用作界面活性劑。然而，基於對健康及環境的危害，壬基酚已被歐盟禁止使用。

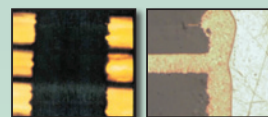
Product 產品	Features and Benefits 特性及效益
RONACLEAN™ EVP 200 Cleaner Series	<ul style="list-style-type: none"> One component acid cleaner 單成份酸性清潔劑 Excellent cleaning performance for dry film and other residues 針對乾膜及其它殘渣，具有絕佳的清潔能力 Capable of pattern process without damaging dry film 適用於線路鍍銅製程，同時並不會損害乾膜
RONASTAN™ EC-1 Tin Plating	<ul style="list-style-type: none"> Matte Tin for etch resist application 霧面錫適用於蝕刻阻劑之應用 Best in class throwing power 最佳且均勻的孔內錫層覆蓋
CRIMSON™ Sensitizer 5123M-1 CIRCUPOSIT™ Conditioner 3323A	<ul style="list-style-type: none"> Excellent and uniform coverage on both glass fiber and resin 在玻璃纖維及樹脂上，皆有絕佳且一致的覆蓋性 Provide optimum Pd adsorption for all laminate and dielectric materials yielding complete electroless copper coverage 在不同板材上，提供最適化之鈀吸附量，助於化學沉銅產生完整的覆蓋 Excellent reliability performance 絕佳的信賴度表現



Excellent detergency without damaging dry film
絕佳的清潔能力，且不損害乾膜



Excellent coverage and resistance
絕佳的錫層覆蓋及抗蝕刻能力



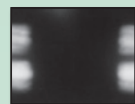
Excellent coverage and reliability performance
絕佳的覆蓋性及信賴度表現

EDTA-free — 不含乙二酸四乙胺

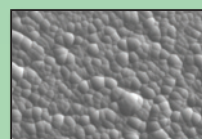
EDTA (Ethylenediaminetetraacetic acid) is a chelating agent. It captures abundant metal ions in solution but itself is not easy to be degraded, making it a persistent organic pollutant.

EDTA作為螯合劑，它於水溶液中補捉大量金屬離子但本身卻不易被分解，使其成為長期有機污染物。

Product 產品	Features and Benefits 特性及效益
CIRCUPOSIT™ 328 Electroless Copper	<ul style="list-style-type: none"> High-yield, "thin" electroless copper, tartrate-based 高附載，薄化學沉銅，酒石酸系統 Excellent plating coverage and copper-to-copper bonds achieved with all electroplate coppers 絕佳的化學銅鍍層覆蓋性，使其與不同的電鍍銅，皆可達成良好的銅與銅連結力
AUROELECTROLESS™ SMT 525G Immersion Gold	<ul style="list-style-type: none"> Low gold content operation with 0.5–1.0 g/L 低金含量操作，金濃度為0.5–1.0 g/L Low gold porosity deposition with very good Ni coverage to avoid corrosion in post treatment process 低疏孔性的化學金層，良好且緻密地覆蓋於鍍層之上，可避免後製程的腐蝕及攻擊 Compatible with ENEPIG and Selective ENIG process 適用於化學鍍鈀金及選擇性化學鍍金製程



Excellent coverage on PI
在PI上具有絕佳的覆蓋能力



No Ni corrosion
無鍍層腐蝕

Formaldehyde-free / HCHO-free — 不含甲醛

Formaldehyde is a strong reducing agent. Nonetheless, it causes health damage by inhalation.

甲醛為一強還原劑。不過，經由吸入會對人體造成健康危害。

Product 產品	Features and Benefits 特性及效益
CRIMSON™ Direct Plating	<ul style="list-style-type: none"> The leading palladium-based direct plate system in horizontal process that creates a stable sulfide conversion coating 硫化鈀系統的直接電鍍製程，適用於水平線，並可產生穩定鍍層
CONDUCTRON™ Direct Plating	<ul style="list-style-type: none"> Unique palladium-based system that creates a conductive direct plate coating with fine quality and high reliability 獨特的鈀系統直接電鍍製程，可產生良好品質及高信賴度的鍍層